

QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS

APRIL 1985 — REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs

- Dependable Texas Instruments Quality and Reliability

description

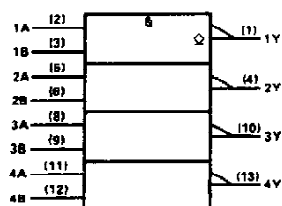
These devices contain four independent 2-input NAND gates. The open-collector outputs require pull-up resistors to perform correctly. They may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices are often used to generate higher V_{OH} levels.

The SN5401 and SN54LS01 are characterized for operation over the full military temperature range of -55°C to 125°C . The SN7401 and SN74LS01 are characterized for operation from 0°C to 70°C .

FUNCTION TABLE (each gate)

INPUTS		OUTPUT
A	B	Y
H	H	L
L	X	H
X	L	H

logic symbol†

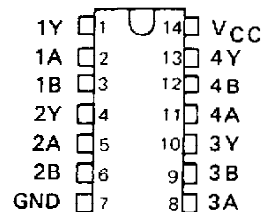


†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

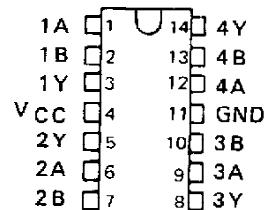
Pin numbers shown are for D, J, N, and W packages.

SN5401 . . . J PACKAGE
SN54LS01 . . . J OR W PACKAGE
SN7401 . . . N PACKAGE
SN74LS01 . . . D OR N PACKAGE

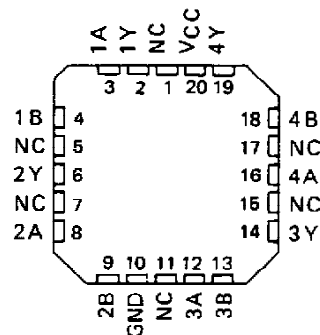
(TOP VIEW)



SN5401 . . . W PACKAGE
(TOP VIEW)



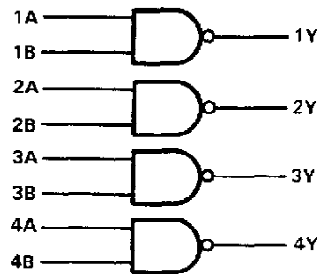
SN54LS01 . . . FK PACKAGE
(TOP VIEW)



NC — No internal connection

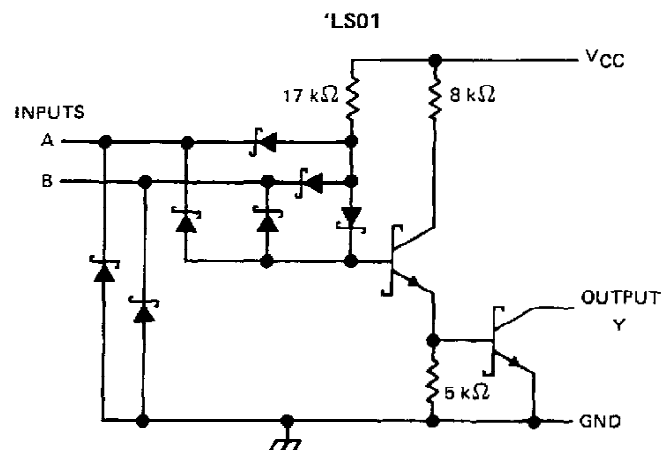
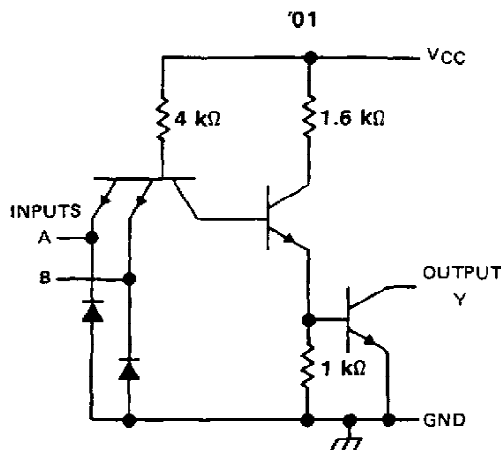
**SN5401, SN54LS01,
SN7401, SN74LS01
QUADRUPL 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS**

logic diagram (positive logic)



positive logic: $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$

schematics (each gate)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1): '01, 'LS01	7 V
Input voltage: '01	5.5 V
'LS01	7 V
Off-state output voltage	7 V
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminals.

**TEXAS
INSTRUMENTS**

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SN5401, SN7401

QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS

recommended operating conditions

	SN5401			SN7401			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.8			0.8	V
V _{OH} High-level output voltage			5.5			5.5	V
I _{OL} Low-level output current			16			16	mA
T _A Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN5401			SN7401			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IK}	V _{CC} = MIN, I _I = -12 mA			-1.5			-1.5	V
I _{OH}	V _{CC} = MIN, V _{IL} = 0.8 V, V _{OH} = 5.5 V						0.25	mA
	V _{CC} = MIN, V _{IL} = 0.7 V, V _{OH} = 5.5 V			0.25				
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 16 mA			0.2			0.4	V
I _I	V _{CC} = MAX, V _I = 5.5 V			1			1	mA
I _{IH}	V _{CC} = MAX, V _I = 2.4 V			40			40	μA
I _{IL}	V _{CC} = MAX, V _I = 0.4 V			-1.6			-1.6	mA
I _{CCH}	V _{CC} = MAX, V _I = 0			4			4	mA
I _{CCL}	V _{CC} = MAX, V _I = 4.5 V			12			12	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	A or B	Y	R _L = 4 kΩ, C _L = 15 pF		35	55	ns
t _{PHL}			R _L = 400 Ω, C _L = 15 pF		8	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

TEXAS
INSTRUMENTS

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SN54LS01, SN74LS01**QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS****recommended operating conditions**

	SN54LS01			SN74LS01			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.7			0.8	V
V _{OH} High-level output voltage			5.5			5.5	V
I _{OL} Low-level output current			4			8	mA
T _A Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS01			SN74LS01			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IK}	V _{CC} = MIN, I _I = -18 mA			-1.5			-1.5	V
I _{OH}	V _{CC} = MIN, V _{IL} = MAX, V _{OH} = 5.5 V			0.1			0.1	mA
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 4 mA	0.25		0.4	0.25		0.4	V
	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 8 mA				0.35		0.5	
I _I	V _{CC} = MAX, V _I = 7 V			0.1			0.1	mA
I _{IH}	V _{CC} = MAX, V _I = 2.7 V			20			20	µA
I _{IL}	V _{CC} = MAX, V _I = 0.4 V			-0.4			-0.4	mA
I _{CCH}	V _{CC} = MAX, V _I = 0	0.8		1.6	0.8		1.6	mA
I _{CCL}	V _{CC} = MAX, V _I = 4.5 V	2.4		4.4	2.4		4.4	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.**switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t _{PLH}	A or B	Y	R _L = 2 kΩ,	C _L = 15 pF		17	32	ns
t _{PHL}						15	28	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN5401J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN7401N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7401N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7401N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7401N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS01D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS01D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS01DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS01DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS01N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS01N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS01N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS01N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SNJ5401J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5401J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5401W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ5401W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS01FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS01FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS01W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS01W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE

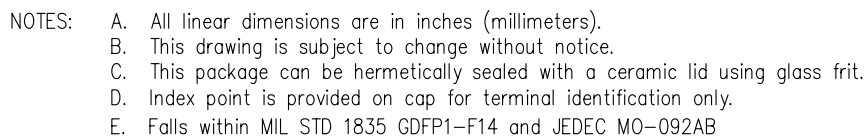


PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.

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